

TOSHIBA RISC PROCESSOR  
**TMPR4927ATB-200**  
(64-bit RISC MICROPROCESSOR)

## 1. GENERAL DESCRIPTION

The TMPR4927ATB, to be referred as TX4927 MIPS RISC micro-controller is a highly integrated ASSP solution based on Toshiba's TX49/H2 processor core, a 64-bit MIPS I,II,III ISA Instruction Set Architecture (ISA) compatible with additional instructions. The TX4927 is a highly integrated device with integrated peripherals such as SDRAM memory controller, PCI controller, PIO, AC-Link, UART and Timer. This class of product is targeted for applications that require a high performance and cost-effective solution such as networking and printers.

## 2. FEATURES

- TX49/H2 core with an integrated IEEE 754-compliant FPU for single- / double-precision operations
- 4-channel SDRAM Controller ( 64-bit 100MHz )
- 8-channel External Bus Controller
- 32-bit PCI Controller ( 32-bit 33 / 66 MHz )
- 4-channel Direct Memory Access ( DMA ) Controller
- 2-channel Serial I/O Port
- Parallel I/O Port (up to 16-bit)
- 3-channel Timer / Counter
- AC-Link ( AC97 Interface )
- Low power dissipation ( Typ. 1.5 W )

The TX4927 operates with the 1.5V Int. and the 3.3V I/O, while supporting a low-power ( Halt ) mode.

- CPU maximum operating frequency: 200 MHz
- IEEE1149.1 (JTAG) support: Debug Support Unit ( Enhanced JTAG )
- 420-pin TBGA

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**2.1 Internal Block Diagram**

Figure 1 shows the TX4927 internal block diagram.

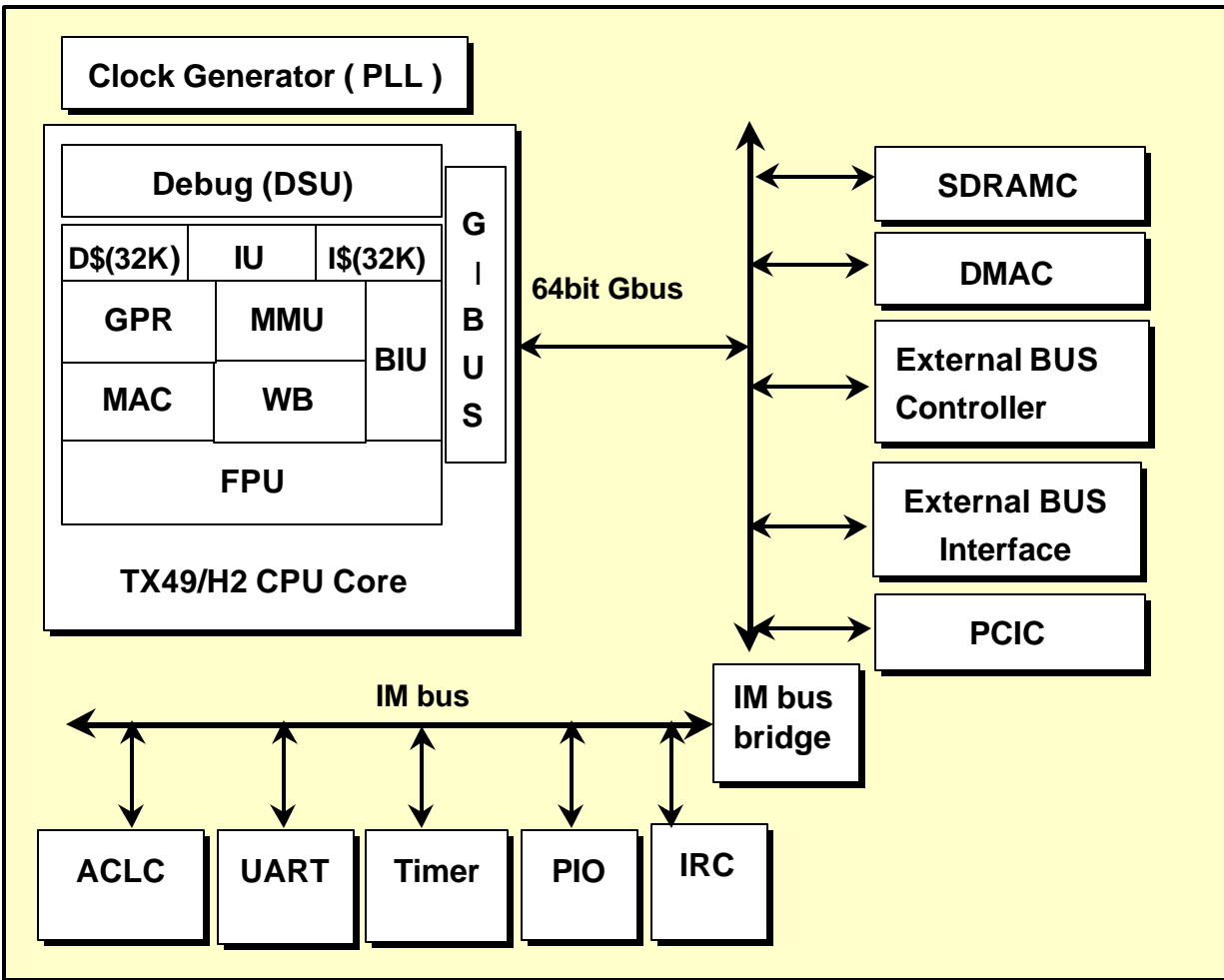


Figure 1 TX4927 Internal Block Diagram

**2.2 System Block Diagram**

Figure 2 shows the system block diagram with TX4927.

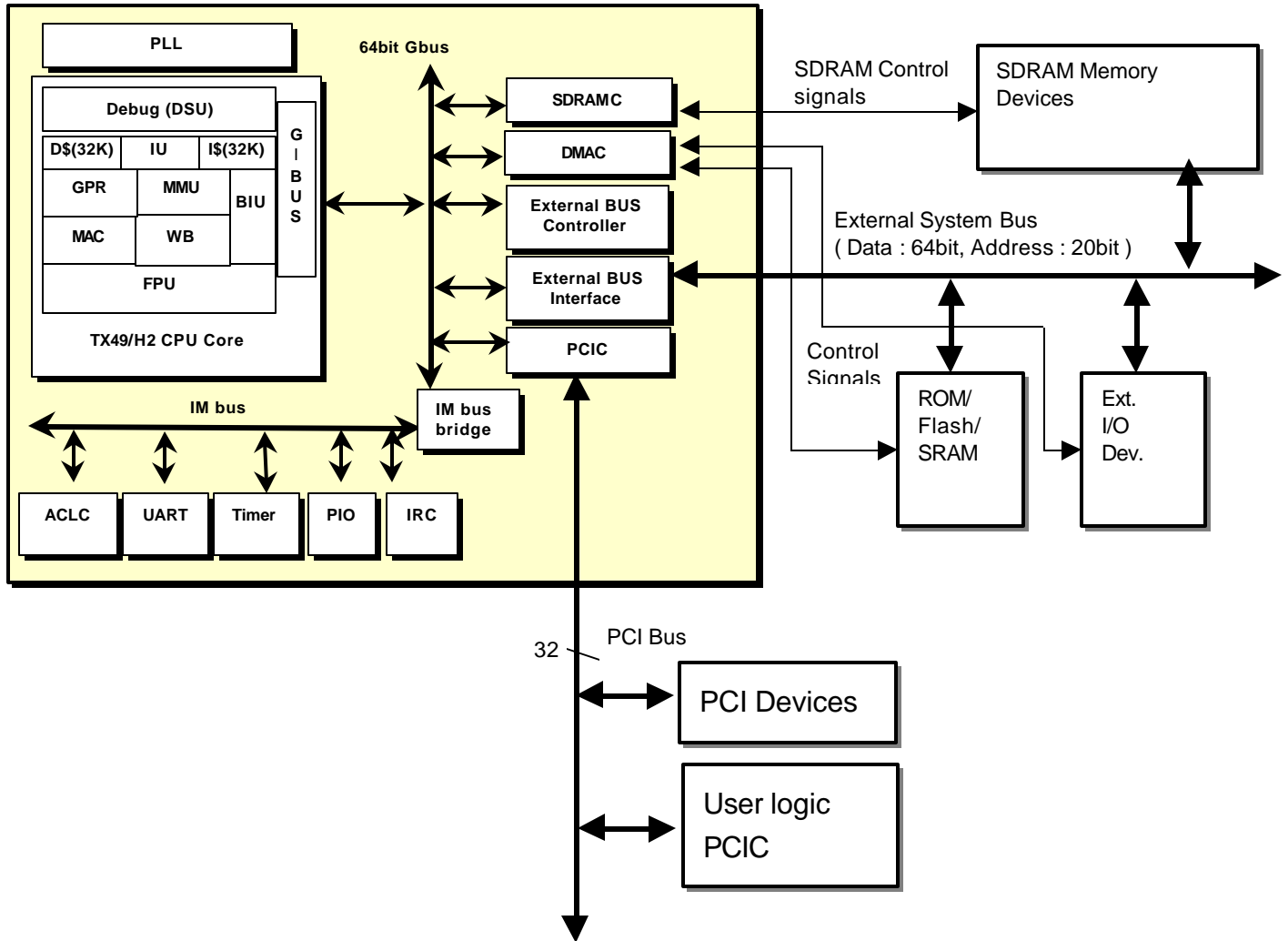


Figure 2 Typical TX4927 System Block Diagram

### 2.3 TX49/H2 Core Block Diagram

Figure 3 shows the internal block diagram of the TX49/H2 core

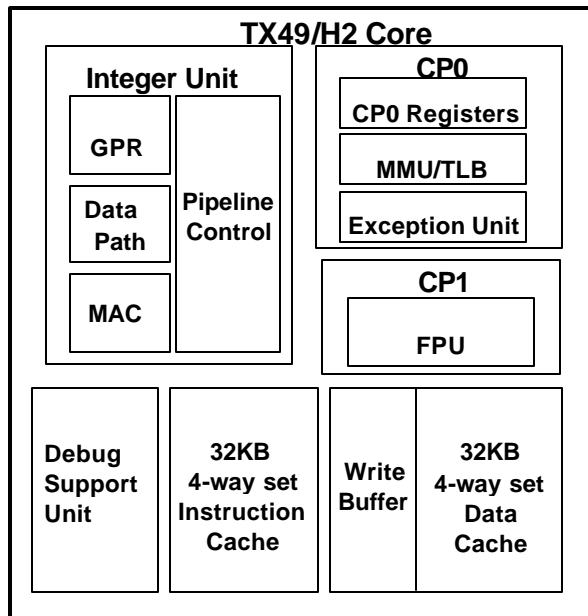


Figure 3 TX49/H2 Core Block Diagram

### 2.4 TX49/H2 CORE FEATURES

The TX49/H2 Core is high performance and low-power 64-bit RISC processor core developed by Toshiba.

- 64-bit operation
- 32, 64-bit integer general purpose registers
- 32-bit physical address space and 64-bit virtual address space
- Optimized 5-stage pipeline
- Instruction Set
  - MIPS I, II, III compatible ISA
  - PREF (Prefetch) and MAC (Multiply/Accumulate) instructions.
- 32k Byte Instruction Cache, and 32k Byte Data Cache
  - 4-way set associative with lock function
- MMU (Memory Management Unit): 48-entry fully associative JTLB
- The on-chip FPU supports both single- and double-precision arithmetic, as specified in IEEE Std 754.
- On-chip 4-deep write buffer
- Enhanced JTAG debug feature
  - Built-in Debug Support Unit (DSU)

## 2.5 TX4927 Peripheral Circuit FEATURES

### ■ External Bus Controller ( EBUSC )

The External Bus Controller generates necessary signals to control external memory and I/O devices.

- 8 channels of chip select signals, enabling control of up to eight devices
- Supports access to ROM ( including mask ROM, page mode ROM, EPROM and EEPROM), SRAM, flash ROM, and I/O devices
- Supports 32-bit, 16-bit and 8-bit data bus sizing on a per channel basis
- Supports selection among full speed ( up to 100MHz ), 1/2 speed ( up to 50MHz), 1/3 speed ( up to 33MHz ) and 1/4 speed ( up to 25MHz) on a per channel basis
- Support specification of timing on a per channel basis
- The user can specify setup and hold times for address, chip enable, write enable, and output enable signals
- Supports memory sizes of 1M byte to 1G byte for devices with 32-bit data bus, 1M byte to 512M bytes for devices with 16-bit data bus, and 1M byte to 256M bytes for devices with 8-bit data bus

### ■ DMA Controller ( DMAC )

The TX4927 contains a 4-channel DMA controller that executes DMA transfer to memory and I/O devices.

- 4-channel independently handling internal / external DMA requests
- Supports DMA transfer with built-in serial I/O controller and AC-link controller based on internal DMA requests
- Supports signal address ( fly-by DMA ) and dual address transfers in external I/O DMA transfer mode using external DMA requests
- Supports transfer between memory and external I/O devices having 32 / 16 / 8-bit data bus
- Supports memory-to-memory copy mode, with no address boundary restrictions
- Supports burst transfer of up to 8 double words for a single read / write
- Supports memory fill mode, writing double-word data to specified memory area
- Supports chained DMA transfer

■ **SDRAM Controller ( SDRAMC )**

The SDRAM Controller generates necessary control signals for the SDRAM interface. It has four channels and can handle up to 2G bytes ( 512 MB/channel ) of memory by supporting a variety of memory configurations.

- Memory clock frequency : 50 to 100MHz
- 4 sets of independent memory channels
- Supports 16M / 64M / 128M / 256M-bit SDRAM with 2/4 bank size availability
- Supports use of Registered DIMM
- Supports ECC or parity generation / check functions
- Supports 64 / 32-bit data bus sizing on a per channel basis
- Supports specification of SDRAM timing on a per channel basis
- Supports critical word first access of TX49/H2 core
- Low power mode : selectable between self-refreshing and pre-charge power-down

■ **PCI Controller ( PCIC )**

The TX4927 contains a PCI Controller that complies with PCI Local Bus Specification Revision 2.2.

- Compliance with PCI Local Bus Specification Revision 2.2
- 32-bit PCI interface featuring maximum PCI bus clock frequency of 66MHz
- Supports both target and initiator functions
- Supports change of address mapping between internal bus and PCI bus
- PCI bus arbiter enables connection of up 4 external bus masters
- Supports booting of TX4927 from memory on PCI bus
- 1 channel of DMA controller dedicated to PCI controller ( PDMAC )

■ **Serial I/O Controller ( UART )**

The TX4927 contains a 2-channels asynchronous serial I/O interface ( full duplex UART ).

- 2-channel full duplex UART
- Built-in baud rate generator
- FIFOs
- 8-bit x 8 transmitter FIFO
- 13-bit ( 8 data bits and 5 status bits ) x 16 receiver FIFO
- Supports DMA transfer

■ **Timers / Counters Controller ( TMR )**

The TX4927 contains 3-channel timer / counters.

- 3-channel 32-bit up-counter
- Supports three modes : interval timer mode, pulse generator mode, and watchdog timer mode
- 2 timer output pins
- 1 count clock input pin
- 1 external watchdog reset signal

■ **Parallel I/O Ports ( PIO )**

The TX4927 contains 16-bit parallel I/O ports ( including 8 bits shared with CB [ 7 : 0 ] ).

- Independent selection of direction of pins and output port type ( totem-pole or open-drain outputs ) on a per bit basis.

■ **AC-link controller ( ACLC )**

The TX4927 contains an AC-link controller, which can be operated using any audio and / or modem CODECs described in Audio CODEC'97 Revision 2.1 ( AC'97 ).

- Supports up to two CODECs
- Supports recording and playback for right and left 16-bit PCM channels
- Supports playback for 16-bit surround, center, and LFE channels
- Supports audio recording and playback at variable rate
- Supports Line1 and GPIO slots for modem CODEC
- Supports AC-link low power mode, wakeup, and warm reset
- Supports input / output of sample data by DMA transfer

■ **Interrupt Controller ( IRC )**

The TX4927 contains an interrupt controller, which receives interrupt requests sent by both the TX4927's built-in peripherals and external devices and issues interrupt requests to the TX49/H2 core. It has a 16-bit flag register to generate interrupt requests to external devices or the TX49/H2 core.

- Supports 18 internal interrupt sources from built-in peripherals and 6 external interrupt signal inputs
- 8 interrupt priority levels for each interrupt source
- Supports selection between edge- and level-triggered interrupt detection for each external interrupt
- 16-bit read / write flag register for interrupt requests, making it possible to issue interrupt request to external devices and to the TX49/H2 core ( IRC interrupts )

■ **Extended EJTAG Interface**

The TX4927 contains an Extended Enhanced Joint Test Action Group ( Extended EJTAG ) interface, which provides two functions : JTAG boundary scan test that complies with IEEE1149.1 and real-time debugging using a debug support unit ( DSU ) built into the TX49/H2 core.

- IEEE 1149.1 JTAG Boundary Scan
- Real-time debugging functions using special emulation probe : execution control ( execution, break, step, and register / memory access ) and PC trace



### 3. Pins

#### 3.1 Pin designations

A1	PIO[1]	B17	PCIAD[0]	D7	CE[0]*	E23	PCIAD[22]	J25	GNT[0]*
A2	PIO[0]	B18	PCIAD[3]	D8	VddIN	E24	PCIAD[21]	J26	PCICLK[1]
A3	SWE*	B19	PCIAD[6]	D9	Vss	E25	PCIAD[20]	K1	RESET*
A4	CE[7]*	B20	PCIAD[8]	D10	VddIN	E26	PCIAD[19]	K2	TEST[0]*
A5	CE[5]*	B21	PCIAD[12]	D11	DMAACK[0]	F1	INT[2]	K3	HALTDOZE
A6	CE[4]*	B22	C_BE[1]	D12	VddIO	F2	INT[1]	K4	VddIN
A7	DMAACK[2]	B23	PERR*	D13	TPC[2]	F3	INT[0]	K5	Vss
A8	DMAACK[1]	B24	STOP*	D14	VddIO	F4	NMI*	K22	Vss
A9	BWE[0]*	B25	FRAME*	D15	VddIN	F5	VddIN	K23	VddIN
A10	BWE[1]*	B26	Vss	D16	VddIO	F22	VddIO	K24	GNT[1]*
A11	EEPROM_DI	C1	PIO[5]	D17	VddIN	F23	C_BE[3]	K25	REQ[0]*
A12	EEPROM_DO	C2	PIO[4]	D18	PCIAD[4]	F24	ID_SEL	K26	PCICLK[2]
A13	Vss	C3	VddIO	D19	VddIO	F25	VddIO	L1	SYSCLK
A14	EEPROM_SK	C4	ACK*	D20	M66EN	F26	PCIAD[23]	L2	TEST[4]*
A15	EEPROM_CS	C5	ACE*	D21	VddIO	G1	INT[5]	L3	TEST[3]*
A16	PCST[3]	C6	CE[2]*	D22	SERR*	G2	INT[4]	L4	TEST[2]*
A17	PCST[0]	C7	CE[1]*	D23	VddIN	G3	INT[3]	L5	TEST[1]*
A18	PCIAD[2]	C8	DMAREQ[3]	D24	TRDY*	G4	RXD[0]	L22	REQ[1]*
A19	PCIAD[5]	C9	VddIO	D25	VddIO	G5	VddIN	L23	Vss
A20	C_BE[0]	C10	BWE[3]*	D26	PCIAD[18]	G22	PCIAD[28]	L24	REQ[2]*
A21	PCIAD[11]	C11	TDI	E1	TCLK	G23	PCIAD[27]	L25	GNT[2]*
A22	PCIAD[15]	C12	TMS	E2	TIMER[0]	G24	PCIAD[26]	L26	PCICLK[3]
A23	Vss	C13	TPC[3]	E3	TIMER[1]	G25	PCIAD[25]	M1	OE*
A24	VddIO	C14	PCST[7]	E4	VddIO	G26	PCIAD[24]	M2	WDRST*
A25	IRDY*	C15	PCST[4]	E5	Vss	H1	TXD[0]	M3	VddIO
A26	C_BE[2]	C16	PCST[1]	E6	SDIN[1]	H2	RTS[0]*	M4	VddIN
B1	PIO[3]	C17	PCIAD[1]	E7	VddIO	H3	CTS[0]*	M5	Vss
B2	PIO[2]	C18	VddIO	E8	Vss	H4	VddIO	M22	Vss
B3	BUSSPRT*	C19	PCIAD[7]	E9	DMADONE*	H5	Vss	M23	VddIO
B4	CE[6]*	C20	PCIAD[9]	E10	Vss	H22	Vss	M24	REQ[3]*
B5	VddIO	C21	PCIAD[13]	E11	DMAREQ[0]	H23	VddIN	M25	GNT[3]*
B6	CE[3]*	C22	PAR	E12	Vss	H24	PCIAD[29]	M26	PCICLK[4]
B7	DMAACK[3]	C23	LOCK*	E13	TPC[1]	H25	VddIO	N1	DATA[1]
B8	DMAREQ[2]	C24	DEVSEL*	E14	PCST[6]	H26	PCICLK[0]	N2	DATA[32]
B9	DMAREQ[1]	C25	PCIAD[17]	E15	Vss	J1	SCLK	N3	DATA[0]
B10	BWE[2]*	C26	PCIAD[16]	E16	TRST*	J2	TXD[1]	N4	Vss
B11	TCK	D1	PIO[7]	E17	Vss	J3	RTS[1]*	N5	VddIO
B12	DCLK	D2	Vss	E18	Vss	J4	CTS[1]*	N22	PME*
B13	TDO	D3	PIO[6]	E19	Vss	J5	RXD[1]	N23	VddIO
B14	PCST[8]	D4	VddIN	E20	PCIAD[10]	J22	PCIAD[31]	N24	Vss
B15	PCST[5]	D5	BYPASSPLL*	E21	PCIAD[14]	J23	Vss	N25	DATA[63]
B16	PCST[2]	D6	Vss	E22	Vss	J24	PCIAD[30]	N26	PCICLK[5]

P1	DATA[2]	V3	VddIO	AB5	Vss	AC21	Vss	AE11	ADDR[9]
P2	Vss	V4	VddIO	AB6	DQM[0]	AC22	DATA[48]	AE12	Vss
P3	DATA[33]	V5	DATA[7]	AB7	VddIO	AC23	VddIN	AE13	ADDR[13]
P4	Vss	V22	VddIO	AB8	Vss	AC24	Vss	AE14	Vss
P5	VddIO	V23	DATA[28]	AB9	ADDR[3]	AC25	DATA[53]	AE15	ADDR[16]
P22	VddIN	V24	Vss	AB10	Vss	AC26	DATA[22]	AE16	ADDR[19]
P23	CGRESET*	V25	DATA[60]	AB11	ADDR[7]	AD1	VddIO	AE17	SDCS[2]*
P24	PLL2Vcc_A	V26	DATA[29]	AB12	Vss	AD2	DATA[46]	AE18	Vss
P25	PLL2Vss_A	W1	DATA[8]	AB13	Vss	AD3	CB[0]	AE19	DQM[3]
P26	PCICLKIN	W2	DATA[39]	AB14	Vss	AD4	Vss	AE20	CB[6]
R1	DATA[35]	W3	Vss	AB15	Vss	AD5	Vss	AE21	VddIO
R2	DATA[3]	W4	VddIN	AB16	ADDR[17]	AD6	DQM[4]	AE22	DATA[49]
R3	DATA[34]	W5	Vss	AB17	Vss	AD7	SDCS[1]*	AE23	Vss
R4	VddIO	W22	Vss	AB18	SDCS[3]*	AD8	Vss	AE24	VddIO
R5	Vss	W23	VddIO	AB19	Vss	AD9	Vss	AE25	DATA[20]
R22	Vss	W24	Vss	AB20	DQM[7]	AD10	ADDR[5]	AE26	VddIO
R23	VddIN	W25	DATA[27]	AB21	CB[3]	AD11	Vss	AF1	Vss
R24	PLL1Vcc_A	W26	DATA[59]	AB22	Vss	AD12	ADDR[10]	AF2	DATA[47]
R25	PLL1Vss_A	Y1	DATA[10]	AB23	VddIO	AD13	ADDR[12]	AF3	CB[1]
R26	MASTERCLK	Y2	DATA[41]	AB24	Vss	AD14	ADDR[14]	AF4	CAS*
T1	Vss	Y3	Vss	AB25	DATA[54]	AD15	ADDR[15]	AF5	Vss
T2	DATA[5]	Y4	DATA[9]	AB26	Vss	AD16	ADDR[18]	AF6	DQM[5]
T3	DATA[36]	Y5	DATA[40]	AC1	DATA[14]	AD17	CKE	AF7	ADDR[0]
T4	VddIO	Y22	VddIO	AC2	Vss	AD18	DQM[6]	AF8	ADDR[2]
T5	DATA[4]	Y23	DATA[25]	AC3	Vss	AD19	Vss	AF9	VddIO
T22	DATA[30]	Y24	DATA[57]	AC4	VddIN	AD20	Vss	AF10	Vss
T23	DATA[62]	Y25	DATA[26]	AC5	VddIO	AD21	CB[7]	AF11	VddIO
T24	VddIO	Y26	DATA[58]	AC6	Vss	AD22	DATA[17]	AF12	ADDR[11]
T25	DATA[31]	AA1	DATA[43]	AC7	SDCS[0]*	AD23	Vss	AF13	SDCLK[2]
T26	Vss	AA2	DATA[11]	AC8	VddIO	AD24	DATA[50]	AF14	SDCLK[0]
U1	DATA[38]	AA3	VddIO	AC9	VddIO	AD25	DATA[52]	AF15	SDCLKIN
U2	DATA[6]	AA4	Vss	AC10	VddIN	AD26	DATA[21]	AF16	Vss
U3	DATA[37]	AA5	DATA[42]	AC11	ADDR[8]	AE1	DATA[15]	AF17	SDCLK[3]
U4	VddIN	AA22	DATA[23]	AC12	VddIN	AE2	VddIO	AF18	Vss
U5	Vss	AA23	Vss	AC13	VddIO	AE3	CB[4]	AF19	SDCLK[1]
U22	Vss	AA24	DATA[55]	AC14	VddIO	AE4	CB[5]	AF20	VddIO
U23	VddIN	AA25	DATA[24]	AC15	VddIO	AE5	WE*	AF21	DATA[16]
U24	VddIO	AA26	DATA[56]	AC16	VddIO	AE6	DQM[1]	AF22	DATA[18]
U25	DATA[61]	AB1	DATA[45]	AC17	VddIN	AE7	RAS*	AF23	VddIO
U26	Vss	AB2	DATA[13]	AC18	DQM[2]	AE8	ADDR[1]	AF24	DATA[19]
V1	Vss	AB3	DATA[44]	AC19	VddIN	AE9	ADDR[4]	AF25	DATA[51]
V2	Vss	AB4	DATA[12]	AC20	CB[2]	AE10	ADDR[6]	AF26	Vss

### 3.2 Pin layout

	A	B	C	D	E	F	G	H	J	K	L	M	N
26	A26	B26	C26	D26	E26	F26	G26	H26	J26	K26	L26	M26	N26
25	A25	B25	C25	D25	E25	F25	G25	H25	J25	K25	L25	M25	N25
24	A24	B24	C24	D24	E24	F24	G24	H24	J24	K24	L24	M24	N24
23	A23	B23	C23	D23	E23	F23	G23	H23	J23	K23	L23	M23	N23
22	A22	B22	C22	D22	E22	F22	G22	H22	J22	K22	L22	M22	N22
21	A21	B21	C21	D21	E21								
20	A20	B20	C20	D20	E20								
19	A19	B19	C19	D19	E19								
18	A18	B18	C18	D18	E18								
17	A17	B17	C17	D17	E17								
16	A16	B16	C16	D16	E16								
15	A15	B15	C15	D15	E15								
14	A14	B14	C14	D14	E14								
13	A13	B13	C13	D13	E13								
12	A12	B12	C12	D12	E12								
11	A11	B11	C11	D11	E11								
10	A10	B10	C10	D10	E10								
9	A9	B9	C9	D9	E9								
8	A8	B8	C8	D8	E8								
7	A7	B7	C7	D7	E7								
6	A6	B6	C6	D6	E6								
5	A5	B5	C5	D5	E5	F5	G5	H5	J5	K5	L5	M5	N5
4	A4	B4	C4	D4	E4	F4	G4	H4	J4	K4	L4	M4	N4
3	A3	B3	C3	D3	E3	F3	G3	H3	J3	K3	L3	M3	N3
2	A2	B2	C2	D2	E2	F2	G2	H2	J2	K2	L2	M2	N2
1	A1	B1	C1	D1	E1	F1	G1	H1	J1	K1	L1	M1	N1

P	R	T	U	V	W	Y	AA	AB	AC	AD	AE	AF	
P26	R26	T26	U26	V26	W26	Y26	AA26	AB26	AC26	AD26	AE26	AF26	26
P25	R25	T25	U25	V25	W25	Y25	AA25	AB25	AC25	AD25	AE25	AF25	25
P24	R24	T24	U24	V24	W24	Y24	AA24	AB24	AC24	AD24	AE24	AF24	24
P23	R23	T23	U23	V23	W23	Y23	AA23	AB23	AC23	AD23	AE23	AF23	23
P22	R22	T22	U22	V22	W22	Y22	AA22	AB22	AC22	AD22	AE22	AF22	22
								AB21	AC21	AD21	AE21	AF21	21
								AB20	AC20	AD20	AE20	AF20	20
								AB19	AC19	AD19	AE19	AF19	19
								AB18	AC18	AD18	AE18	AF18	18
								AB17	AC17	AD17	AE17	AF17	17
								AB16	AC16	AD16	AE16	AF16	16
								AB15	AC15	AD15	AE15	AF15	15
								AB14	AC14	AD14	AE14	AF14	14
								AB13	AC13	AD13	AE13	AF13	13
								AB12	AC12	AD12	AE12	AF12	12
								AB11	AC11	AD11	AE11	AF11	11
								AB10	AC10	AD10	AE10	AF10	10
								AB9	AC9	AD9	AE9	AF9	9
								AB8	AC8	AD8	AE8	AF8	8
								AB7	AC7	AD7	AE7	AF7	7
								AB6	AC6	AD6	AE6	AF6	6
P5	R5	T5	U5	V5	W5	Y5	AA5	AB5	AC5	AD5	AE5	AF5	5
P4	R4	T4	U4	V4	W4	Y4	AA4	AB4	AC4	AD4	AE4	AF4	4
P3	R3	T3	U3	V3	W3	Y3	AA3	AB3	AC3	AD3	AE3	AF3	3
P2	R2	T2	U2	V2	W2	Y2	AA2	AB2	AC2	AD2	AE2	AF2	2
P1	R1	T1	U1	V1	W1	Y1	AA1	AB1	AC1	AD1	AE1	AF1	1

### 3.3 Pin Description

Note: In the I/O columns, "PU" indicates an I/O pin with a pull-up resistor, and the term "OD" indicates an open drain output. \* denotes an active-low signal when used as a suffix to a signal name.

Signal Name	Type	Function
<b>SDRAM / External Bus Interface Common Signals</b>		
<b>ADDR[19:0]</b>	<b>I/O PU</b>	<p><b>Addresses</b></p> <p>Address signals.</p> <p>For SDRAM, ADDR[19:5] are used .</p> <p>When the external bus controller uses these pins, the meaning of each bit varies with the data bus width. The ADDR signals are also used as boot configuration signals (input) during a reset.</p> <p>ADDR signals are input signals only when the RESET* signal is asserted and become output signals after the RESET* signal is de-asserted.</p>
<b>DATA[63:0]</b>	<b>I/O PU</b>	<p><b>Data Bus</b></p> <p>64-bit data bus.</p> <p>The DATA[15:0] signals are also used as boot configuration signals (input) during a reset.</p>
<b>BUSSPRT*</b>	<b>O</b>	<p><b>BUS Separate</b></p> <p>Controls the connection and separation of devices controlled by the external bus controller to or from a high-speed device, such as SDRAM.</p> <p>H: Separate devices other than SDRAM from the data bus.</p> <p>L: Connect devices other than SDRAM to the data bus.</p> <p>Separation and connection are performed using external bi-directional bus buffers (such as the 74xx245).</p>

Signal Name	Type	Function
<b>SDRAM Interface Signals</b>		
<b>SDCLK[3:0]</b>	<b>O</b>	<b>SDRAM Controller Clock</b> Clock signals used by SDRAM. The clock frequency is the same as the G-Bus clock (GBUSCLK) frequency. When these clock signals are not used, the pins can be set to H using the SDCLK Enable field of the configuration register (CCFG.SDCLKEN[3:0]).
<b>SDCLKIN</b>	<b>I/O</b>	<b>SDRAM feedback clock input</b> Feedback clock signal for SDRAM controller input signals. Setting the SDCLKINEN bit of the pin configuration register causes the TX4927 to feed back signals internally, making SDCLKIN an output signal.
<b>CKE</b>	<b>O</b>	<b>Clock Enable</b> CKE signal for SDRAM.
<b>SDCS[3:0]*</b>	<b>O</b>	<b>Synchronous Memory Device Chip Select</b> Chip select signals for SDRAM.
<b>RAS*</b>	<b>O</b>	<b>Row Address Strobe</b> RAS signal for SDRAM.
<b>CAS*</b>	<b>O</b>	<b>Column Address Strobe</b> CAS signal for SDRAM.
<b>WE*</b>	<b>O</b>	<b>Write Enable</b> WR signal for SDRAM.

Signal Name	Type	Function
<b>DQM[7:0]</b>	<b>O</b>	<p><b>Data Mask</b></p> <p>During a read cycle, they control the SDRAM output buffers. The bits correspond to the following data bus signals:</p> <p>DMQ[7] : DATA[63:54], DMQ[6] : DATA[53:48]  DMQ[5] : DATA[47:40], DMQ[4] : DATA[39:32]  DMQ[3] : DATA[31:24], DMQ[2] : DATA[23:16]  DMQ[1] : DATA[15:8], DMQ[0] : DATA[7:0]</p>
<b>CB[7:0]</b>	<b>I/O PU</b>	<p><b>ECC control or Data parity</b></p> <p>ECC/parity check bit signals. The bits correspond to the following data bus signals:.</p> <p>CB[7] : DATA[63:54], CB[6] : DATA[53:48]  CB[5] : DATA[47:40], CB[4] : DATA[39:32]  CB[3] : DATA[31:24], CB[2] : DATA[23:16]  CB[1] : DATA[15:8], CB[0] : DATA[7:0]</p> <p>CB[7:0] share pins with the PIO[15:8] signals for parallel I/O. The boot configuration signal on the ADDR[18] pin selects between PIO[15:8] and CB[7:0].</p>

Signal Name	Type	Function
<b>External Bus Interface Signals</b>		
<b>SYSCLK</b>	<b>O</b>	<b>System Clock</b> Clock for external I/O devices. Outputs a clock in full speed mode (at the same frequency as the G-Bus clock (GBUSCLK) frequency), half speed mode (at one half the GBUSCLK frequency), third speed mode (at one third the GBUSCLK frequency), or quarter speed mode (at one quarter the GBUSCLK frequency). The boot configuration signals on the ADDR[14:13] pins select which speed mode will be used. When this clock signal is not used, the pin can be set to H using the SYSCLK Enable bit of the configuration register (CCFG.SYSCLKEN).
<b>ACE*</b>	<b>O</b>	<b>Address Clock Enable</b> Latch enable signal for the high-order address bits of ADDR.
<b>CE [7:0]*</b>	<b>O</b>	<b>Chip Enable</b> Chip select signals for ROM, SRAM, and I/O devices.
<b>OE*</b>	<b>O</b>	<b>Output Enable</b> Output enable signal for ROM, SRAM, and I/O devices.
<b>SWE*</b>	<b>O</b>	<b>Static RAM Write Enable</b> Write enable signal for SRAM and I/O devices.
<b>BWE[3:0]* / BE[3:0]*</b>	<b>O</b>	<b>Byte Write Enable / Byte Enable</b> BE[3:0]* indicate valid data position on the data bus DATA[31:0] at both read and write bus operation. In 16-bit bus mode, BE[1:0]* is only used. In 8-bit bus mode, BE[0]* is only used. BWE[3:0]* indicate valid data position on the data bus DATA[31:0] at write bus operation. In 16-bit bus mode, BWE[1:0]* is only used. In 8-bit bus mode, BWE[0]* is only used. The following shows the correspondence between BE[3:0]*/BWE[3:0]* and the data bus. BE[3]* / BWE[3]* : DATA[31:24]      BE[1]* / BWE[1]* : DATA[15:8] BE[2]* / BWE[2]* : DATA[23:16]      BE[0]* / BWE[0]* : DATA[7:0] The function of these signals can be selected from BE[3:0]* and BWE[3:0]* by using the DATA[5] signal and the EBCCRn and BC registers in the External Bus Controller during boot-mode configuration.
<b>ACK* / READY</b>	<b>I/O PU</b>	<b>Acknowledge</b> Flow control signal.



Signal Name	Type	Function
<b>DMA Interface</b>		
<b>DMAREQ[3:0]</b>	<b>I PU</b>	<b>DMA Request</b> DMA transfer request signals from an external I/O device. The DMAREQ[2] signal shares the pin with the ACRESET* signal. The boot configuration signal on the ADDR[9] pin selects between DMAREQ[2] and ACRESET*.
<b>DMAACK[3:0]</b>	<b>O</b>	<b>DMA Acknowledge</b> DMA transfer acknowledge signals to an external I/O device. The DMAACK[2] signal shares the pin with the SYNC signal. The boot configuration signal on the ADDR[9] pin selects between DMAACK[2] and SYNC.
<b>DMADONE*</b>	<b>I/O PU</b>	<b>DMA Transfer/Chain Finished</b> DMADONE* is either used as an output signal that reports the termination of DMA transfer or as an input signal that causes DMA transfer to terminate.

<b>PCI Interface</b>		
<b>PCICLK[5:0]</b>	<b>O</b>	<b>PCI Clock</b> PCI bus clock signals. When these clock signals are not used, the pins can be set to H using the PCICLK Enable field of the pin configuration register (PCFG.PCICLKEN[5:0]).
<b>PCICLKIN</b>	<b>I</b>	<b>PCI feedback clock input</b> PCI feedback clock input.
<b>PCIAD[31:0]</b>	<b>I/O</b>	<b>PCI Address and Data</b> Multiplexed address and data bus.
<b>C_BE[3:0]</b>	<b>I/O</b>	<b>Bus Command and Byte Enable</b> Command and byte enable signals.

Signal Name	Type	Function
PAR	I/O	<b>Parity</b> Even parity signal for PCIAD[31:0] and C_BE[3:0]*.
FRAME*	I/O	<b>Cycle</b> Indicates that bus operation is in progress.
IRDY*	I/O	<b>Initiator ready</b> Indicates that the initiator is ready to complete data transfer.
TRDY*	I/O	<b>Target ready</b> Indicates that the initiator is ready to complete data transfer.
STOP*	I/O	<b>STOP</b> The target sends this signal to the initiator to request termination of data transfer.
LOCK*	I	<b>PCI resource clock</b> Indicates that the PCI bus master is locking (exclusively accessing) a specified memory target on the PCI bus.
ID_SEL	I	<b>Initialization Device select</b> Chip select signal used for configuration access.
DEVSEL*	I/O	<b>Device select</b> The target asserts this signal in response to access from the initiator.
REQ[3:2]*	I	<b>Request PCI bus</b> Signals used by the master to request bus mastership.  The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, REQ[3:2]* are PCI bus request input signals. In external arbiter mode, REQ[3:2]* are not used. Because the pins are still placed in the input state, they must be pulled up externally.

Signal Name	Type	Function
REQ[1]* / INOUT	I/O / OD	<b>Request PCI bus</b>  Signal used by the master to request bus mastership. The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, this signal is a PCI bus request input signal. In external arbiter mode, this signal is an external interrupt output signal (INTOUT).
REQ[0]*	I/O	<b>Request PCI bus</b>  Signal used by the master to request bus mastership. The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, this signal is a PCI bus request input signal. In external arbiter mode, this signal is a PCI bus request output signal.
GNT[3:0]*	I/O	<b>Grant PCI bus</b>  Indicates that bus mastership has been granted to the PCI bus master. The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, all of GNT[3:0]* are PCI bus grant output signals. In external arbiter mode, GNT[0]* is a PCI bus grant input signal. Because GNT[3:1]* also become input signals, they must be pulled up externally.
PERR*	I/O	<b>Data Parity Error</b>  Indicates a data parity error in a bus cycle other than special cycles.
SERR*	I/OD	<b>System Error</b>  Indicates an address parity error, a data parity error in a special cycle, or a fatal error. In host mode, SERR* is an input signal. In satellite mode, SERR* is an open-drain output signal. The mode is determined by the boot configuration signal on the ADDR[19] pin.

Signal Name	Type	Function
<b>M66EN</b>	<b>I/O</b>	<b>66MHz clock enable</b> 1: Enable 66 MHz operating mode. 0: Disable 66 MHz operating mode. In host mode, M66EN is an input signal. In satellite mode, M66EN is an output signal. The mode is determined by the boot configuration signal on the ADDR[19] pin.
<b>PME*</b>	<b>I/ OD</b>	<b>Power management event</b> PME* indicates the power management mode. In host mode, PME* is an input signal. In satellite mode, PME* is an open-drain output signal. The mode is determined by the boot configuration signal on the ADDR[19] pin.
<b>EEPROM_DI</b>	<b>I PU</b>	<b>EEPROM data in</b> This is a data input signal from a serial EEPROM for PCI configuration.
<b>EEPROM_DO</b>	<b>O</b>	<b>EEPROM data out</b> This is a data output signal to a serial EEPROM for PCI configuration.
<b>EEPROM_CS</b>	<b>O</b>	<b>EEPROM chip select</b> This is a chip select signal for a serial EEPROM for PCI configuration.
<b>EEPROM_SK</b>	<b>O</b>	<b>EEPROM SK</b> This is a clock signal for a serial EEPROM for PCI configuration.

<b>Timer Interface</b>		
<b>TIMER[1:0]</b>	<b>O</b>	<b>Timer Pulse Width Output</b> Timer output signal.
<b>TCLK</b>	<b>I PU</b>	<b>External Timer Clock</b> Timer input clock. TMR0, TMR1 and TMR2 share this signal.
<b>WDRST*</b>	<b>OD</b>	<b>Watchdog Reset</b> Watchdog reset output signal.

Signal Name	Type	Function
<b>SIO Interface</b>		
CTS[1:0]*	I PU	<b>SIO Clear to Send</b> CTS signals.
RTS[1:0]*	O	<b>SIO Request to Send</b> RTS signals.
RXD[1:0]	I PU	<b>SIO Receive Data</b> Serial data input signal.
TXD[1:0]	3state O	<b>SIO Transmit Data</b> Serial data output signal.
SCLK	I PU	<b>External Serial Clock</b> Input clock for SIO0 and SIO1. SIO0 and SIO1 share this signal.

<b>PIO Interface</b>		
PIO[15:8]	I/O PU	<b>PIO Ports</b> Parallel I/O signals. PIO[15:8] share pins with the SDRAM ECC/parity signals (CB[7:0]). The boot configuration signal on the ADDR[18] pin selects between PIO[15:8] and CB[7:0].
PIO[7:0]	I/O	<b>PIO Ports</b> Parallel I/O signals. PIO[4:2] share pins with the AC-link interface signals (SDOUT, SDIN[0], and BITCLK). The boot configuration signal on the ADDR[9] pin selects between PIO[4:2] and AC-link interface signals.

Signal Name	Type	Function
<b>AC-Link Interface</b>		
<b>ACRESET*</b>	<b>O</b>	<b>AC '97 Master H/W Reset</b> ACRESET* shares the pin with the DMAREQ[2] signal. The boot configuration signal on the ADDR[9] pin selects between ACRESET* and DMAREQ[2].PIO[15:8] and CB[7:0].
<b>SYNC</b>	<b>O</b>	<b>48 kHz Fixed Rate Sample Sync</b> SYNC shares the pin with the DMAACK[2] signal. The boot configuration signal on the ADDR[9] pin selects between SYNC and DMAACK[2].
<b>SDOUT</b>	<b>O</b>	<b>Serial, Time Division Multiplexed, AC '97 Output Stream</b> SDOUT shares the pin with the PIO[4] signal. The boot configuration signal on the ADDR[9] pin selects between SDOUT and PIO[4].
<b>SDIN[1]</b>	<b>I</b>	<b>Serial, Time Division Multiplexed, AC '97 Input Stream</b>
<b>SDIN[0]</b>	<b>I</b>	<b>Serial, Time Division Multiplexed, AC '97 Input Stream</b> SDIN[0] shares the pin with the PIO[3] signal. The boot configuration signal on the ADDR[9] pin selects between SDIN[0] and PIO[3].
<b>BITCLK</b>	<b>I</b>	<b>Serial, Time Division Multiplexed, AC '97 Input Stream</b> BITCLK shares the pin with the PIO[2] signal. The boot configuration signal on the ADDR[9] pin selects between BITCLK and PIO[2].

<b>Interrupt Signals</b>		
<b>NMI*</b>	<b>I PU</b>	<b>Non Mask-able Interrupt</b> Non-Mask-able interrupt input.
<b>INT[5:0]</b>	<b>I PU</b>	<b>External Interrupt Requests</b> The external interrupt request signals.

Signal Name	Type	Function
<b>EJTAG Debug Interface</b>		
<b>TCK</b>	<b>I PU</b>	<b>JTAG clock input</b> Clock input signal for JTAG. TCK is used to execute JTAG instructions and input/output data.
<b>TDI / DINT*</b>	<b>I PU</b>	<b>JTAG data input / Debug interrupt input</b> When PC trace mode is not selected, this signal is a JTAG data input signal. It is used to input serial data to JTAG data/instruction registers. When PC trace mode is selected, this signal is an interrupt input signal used to cancel PC trace mode for the debug unit.
<b>TDO / TPC[0]</b>	<b>O</b>	<b>JTAG data output / PC Trace output</b> When PC trace mode is not selected, this signal is a JTAG data output signal. Data is output by means of serial scan. When PC trace mode is selected, this signal outputs the value of the noncontiguous program counter in sync with the debug clock (DCLK).
<b>TPC[3:1]</b>	<b>O</b>	<b>PC Trace Output</b> TPC[3:1] output the value of the noncontiguous program counter in sync with DCLK.
<b>TMS</b>	<b>I PU</b>	<b>JTAG command</b> TMS mainly controls state transition in the TAP controller state machine.
<b>TRST*</b>	<b>I</b>	<b>Test Reset Input</b> Asynchronous reset input for the TAP controller and debug support unit. When an EJTAG probe is not connected, this pin must be fixed to low. When connecting an EJTAG probe, prevent floating, for example, by connecting a pull-up resistor. When this signal is de-asserted, G-Bus timeout detection is disabled.
<b>DCLK</b>	<b>O</b>	<b>Debug Clock</b> A clock output for a real-time debug system. The timing of a serial monitor bus and PC trace interface signal are all defined by this debug clock DCLK. 3 divide the operation clock of the TMPR4927TB at the time of a serial monitor bus operation.

Signal Name	Type	Function
PCST[8:0]	O	<b>PC Trace Status</b> Output PC trace status information and the mode of the serial monitor bus.

Clock Signals		
MASTERCLK	I	<b>Master Clock Input</b> Input pin for the TX4927 operating clock. A crystal resonator cannot be connected to this pin because the pin does not contain an oscillator.
HALTDOZE	O	<b>Halt/Doze state output</b> This signal is asserted (High output) when the TX4927 enters Halt or Doze mode.
BYPASSPLL*	I	<b>PLL Reset</b> This pin must be fixed to High.
CGRESET*	I	<b>CG Reset</b> CGRESET* initializes the CG

Reset signals		
RESET*	I	<b>Reset</b> Reset signal.

Test signals		
TEST[4:0]*	I PU	<b>Test mode Enable</b> Test pins. These pins must be left open or fixed to High.



Signal Name	Type	Function
<b>Power pins and Total pin count</b>		
PLL1Vdd_A, PLL2Vdd_A, PLL1Vss_A, PLL2Vss_A	-	<b>Power and Ground pins to internal PLL circuit.</b>  PLL1Vcc_A and PLL2Vcc_A = 1.5V, PLL1_Vss_A and PLL2_Vss_A = GND
VddIN	-	<b>Internal Power Pins</b>  Power pins at 1.5V
VddIO	-	<b>I/O Power Pins</b>  Power pins at 3.3V
Vss	-	<b>Ground</b>  Digital ground pins. Vss = 0 V.

## 4. Pin Multiplexing

A total of 13 pins of the TX4927 have multiplexed functions. Table 4.1 shows the multiplexed pins. The function of a given pin is selected in various ways, depending on the pin(s) involved. Table 4.2 and Table 4.3 show the setting by booting of TX4927.

Table 4.1 Pin Multiplexing

Signal name	Multiplexed Function
CB[7:0]	CB[7:0] / PIO[15:8]
DMAREQ[2]	DMAREQ[2] / ACRESET*
DMAACK[2]	DMAACK[2] / SYNC
PIO[4:2]	PIO[4:2] / SDOUT, SDIN[0], BITCLK

Table 4.2 Setting by ADDR[18]

Signal name	ADDR[18]=0 (Non ECC)		ADDR[18]=1 (ECC)	
CB[7:0]	I/O	PIO[15:8]	I/O	CB[7:0]

Table 4.3 Setting by ADDR[9]

Signal name	ADDR[9]=1 (ACLC)		ADDR[9]=0 (Non ACLC)	
DMAREQ[2]	O	ACRESET*	I	DMAREQ[2]
DMAACK[2]	O	SYNC	O	DMAACK[2]
PIO[4]	O	SDOUT	I/O	PIO[4]
PIO[3]	I	SDIN[0]	I/O	PIO[3]
PIO[2]	I	BITCLK	I/O	PIO[2]

## 5. ELECTRICAL CHARACTERISTICS

### 5.1 ABSOLUTE MAXIMUM RATING (\*1)

PARAMETER	SYMBOL	RATING	UNIT
Supply voltage (for I/O)	V <sub>ddIO</sub> Max	-0.3 to 3.9	V
Supply voltage (for internal)	V <sub>CCInt</sub> Max	-0.3 to 3.0	V
Input voltage (*2)	V <sub>IN</sub>	-0.3 to V <sub>ddIO</sub> + 0.3V	V
Storage Temperature	T <sub>STG</sub>	-40 to +125	°C
Power	P <sub>D</sub>	1.5 (Typ.)	W

Note) (\*1) If LSI is used above the maximum ratings, permanent destruction of LSI can result. In addition, it is desirable to use LSI for normal operation under the recommended condition. If these conditions are exceeded, reliability of LSI may be adversely affected.

(\*2) The maximum rated V<sub>ddIO</sub>Max voltage must not be exceeded even at V<sub>ddIO</sub> + 0.3 volts.

### 5.2 RECOMMENDED OPERATING CONDITIONS (\*3)

PARAMETER		SYMBOL	CONDITION	MIN.	MAX.	UNIT
Supply Voltage	I/O	V <sub>ddIO</sub>		3.1	3.5	V
	Internal	V <sub>ddIN</sub>		1.4	1.6	V
Operating Case Temperature		T <sub>c</sub>		0	70	°C

(\*3) Functional operation should be restricted to the recommended operating conditions. Those are the limits under which proper device operation is guaranteed. Therefore, the end product must be designed within the recommended voltage and temperature ranges indicated.

### 5.3 DC CHARACTERISTICS

#### DC Characteristics except for PCI interface

(Tc = 0 ~ 70°C, VddIO = 3.3V ±0.2V, VddIN = 1.5V ± 0.1V, Vss = 0V)

PARAMETER	SYM	CONDITIONS	MIN.	MAX.	UNIT
Low-level input voltage	V <sub>IL1</sub>	(*1)	-0.3	0.8	V
High-level input voltage	V <sub>IH1</sub>	(*1)	2.0	VddIO+0.3	V
Low-level output current	I <sub>OL1</sub>	(*2) V <sub>OL</sub> = 0.4V	8	-	mA
	I <sub>OL2</sub>	(*3) V <sub>OL</sub> = 0.4V	4	-	mA
Low-level output current	I <sub>OL3</sub>	(*4) V <sub>OL</sub> = 0.4V	16	-	mA
	I <sub>OL4</sub>	(*5) V <sub>OL</sub> = 0.4V	8	-	mA
High-level output current	I <sub>OH1</sub>	(*2) V <sub>OH</sub> = 2.4V	-	-8	mA
	I <sub>OH2</sub>	(*3) V <sub>OH</sub> = 2.4V	-	-4	mA
High-level output current	I <sub>OH3</sub>	(*4) V <sub>OH</sub> = 2.4V	-	-16	mA
	I <sub>OH4</sub>	(*5) V <sub>OH</sub> = 2.4V	-	-8	mA
Low-level input leakage current	I <sub>IL1</sub>	(*6) V <sub>IN</sub> = V <sub>SS</sub>	-10	10	μA
	I <sub>IL2</sub>	(*7) V <sub>IN</sub> = V <sub>SS</sub>	-200	-10	μA
High-level input leakage current	I <sub>IH1</sub>	(*8) V <sub>IN</sub> = V <sub>CCIO</sub>	-10	10	μA
	I <sub>IH2</sub>	(*9) V <sub>IN</sub> = V <sub>CCIO</sub>	10	200	μA
Hi-z output leakage current	I <sub>OZ</sub>	(*10)	-10	10	μA
Operating current (for internal)	I <sub>CCInt</sub>	VddIO = 3.3V, VddIN = 1.6V, MASTERCLK=100MHz PClock = 200MHz		600	mA
Operating current (for I/O)	I <sub>CCIO</sub>	VddIO = 3.5V, VddIN = 1.5V, MASTERCLK=100MHz PClock = 200MHz Load=25pF		160	mA

(\*1) All input and input-mode bidirectional pins except PCI interface signals

(\*2) ACE\*, ACK\*, BUSSPRT\*, BWE[3:0]\*, CE[7:0]\*, DMAACK[3:0], DMADONE\*, EEPROM\_CS, EEPROM\_DO, EEPROM\_SK, HALTDOZE, PIO[7:0], RTS[1:0], SWE\*, SYSCLK, TIMER[1:0], TXD[1:0]

(\*3) DCLK, PCST[8:0], TDO, TPC[3:1]

(\*4) Applies to ADDR[19:0], CAS\*, CB[7:0], CKE, DATA[63:0], DQM[7:0], OE\*, RAS\*, SDCLK[3:0], SDCLKIN, SDCS[3:0]\* and WE when an output buffer drive strength of 16 mA is used.

(\*5) Drive 8mA: ADDR[19:0], CAS\*, CB[7:0], CKE, DATA[63:0], DQM[7:0], OE\*, RAS\*, SDCLK[3:0], SDCLKIN, SDCS[3:0]\*, WE

(\*6) EEPROM\_DI, CGRESET\*, RESET\*, TRST\*, BYPASSPLL\*, MASTERCLK, DMADONE\*, PIO[7:0], SDCLKIN

(\*7) CTS[1:0]\*, DMAREQ[3:0], RXD[1:0], SCLK, TCLK, INT[5:0], TCK, TDI, TEST[4:0]\*, TMS, ACK\*, CB[7:0], DATA[63:0], ADDR[19:0], NMI\*

(\*8) (\*6), (\*7) Signals except for TRST\*

(\*9) TRST\*

(\*10) TXD[1:0]

### DC Characteristics except for PCI interface

(Tc = 0 ~ 70°C, VddIO = 3.3V ± 0.2V, VddIN = 1.5V ± 0.1V, Vss = 0V)

PARAMETER	SYM	CONDITIONS	MIN.	MAX.	UNIT
Low-level input voltage	V <sub>ILPCI</sub>	(*1)	-0.5	0.9	V
High-level input voltage	V <sub>IHPCI</sub>	(*1)	1.8	VddIO+0.3	V
High-level output voltage	V <sub>OHPCI</sub>	(*2) I <sub>OUT</sub> = -500µA	VddIO × 0.9	-	V
Low-level output voltage	V <sub>OLPCI</sub>	(*2) I <sub>OUT</sub> = 1500µA	-	VddIO × 0.1	V
Input leakage current	I <sub>IHPCI</sub>	0 < V <sub>IN</sub> < VddIO	-10	10	µA
	I <sub>ILPCI</sub>		-10	10	µA
Hi-z output leakage current	I <sub>OZPCI</sub>	(*3)	-10	10	µA

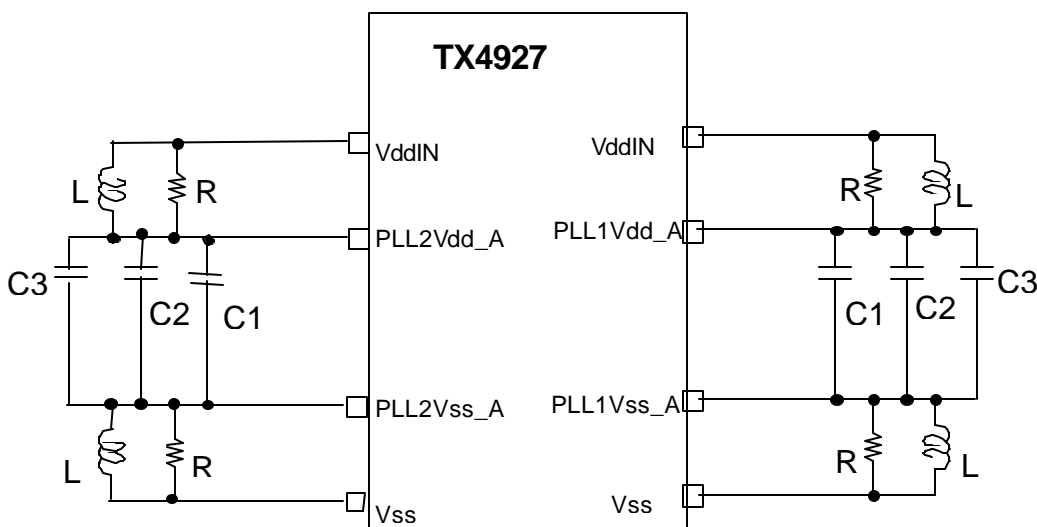
(\*1) ID\_SEL, PCICLKIN, C\_BE[3:0], DEVSEL\*, FRAME\*, GNT[3:0]\*, IRDY\*, LOCK\*, M66EN, PAR, PCIAD[31:0], PERR\*, REQ[3:0], SERR\*, STOP\*, TRDY\*

(\*2) ID\_SEL, PCICLKIN

(\*3) PCICLK[5:0], PME\*

### Power circuit for PLL

Recommended circuit for PLL



Note) C1, CS, C3, R and L should be placed as closed to the processor as possible.

PARAMETER	SYMBOL	AS a reference Value	UNIT
Resistor	R	5	ohm
Inductance	L	T.B.D.	µH
Capacitor	C1	1	nF
	C2	82	nF
	C3	10	µF
VddIN, PLL1Vdd_A, PLL2Vdd_A		1.5V ± 0.1V	V

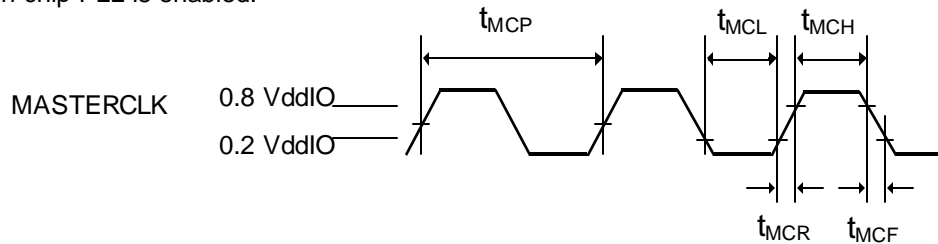
## 5.5 AC CHARACTERISTICS

### MASTERCLK AC Characteristics

( $T_c = 0 \sim 70^\circ\text{C}$ ,  $V_{ddIO} = 3.3\text{V} \pm 0.2\text{V}$ ,  $V_{ddIN} = 1.5\text{V} \pm 0.1\text{V}$ ,  $V_{SS} = 0\text{V}$ )

PARAMETER	SYM	CONDITION	MIN.	MAX.	UNIT
MASTERCLK Period	$t_{MCP}$	ADDR[2]=H in boot time	10	80	ns
MASTERCLK Frequency (*1)	$f_{MCK}$	ADDR[2]=H in boot time	12.5	100	MHz
MASTERCLK High	$t_{MCH}$		3		ns
MASTERCLK Low	$t_{MCL}$		3		ns
Internal Operating Frequency	$f_{CPU}$		50	200	MHz
MASTERCLK Rise Time	$t_{MCR}$			2	ns
MASTERCLK Fall Time	$t_{MCF}$			2	ns

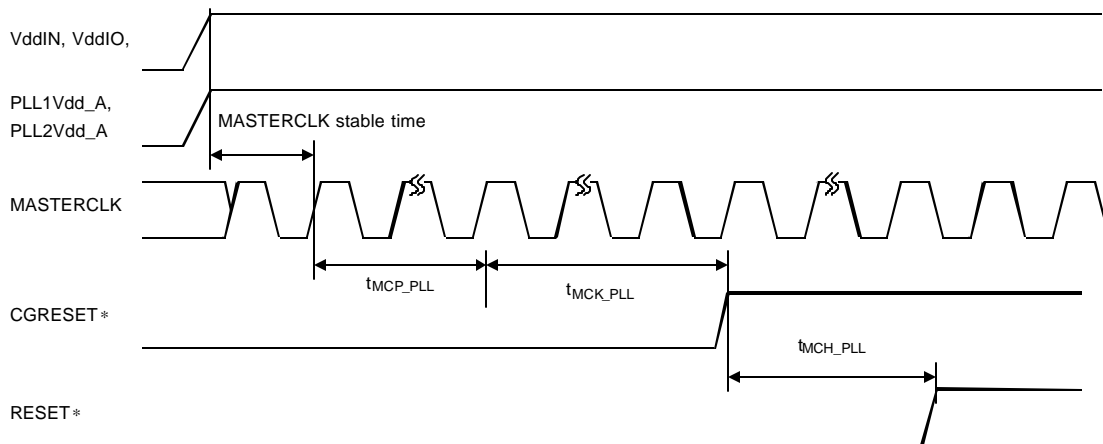
(\*1) Proper circuit operation of the TX4927 is guaranteed only when power supply to it is stable and the on-chip PLL is enabled.



### Power On AC Characteristics

( $T_c = 0 \sim 70^\circ\text{C}$ ,  $V_{ddIO} = 3.3\text{V} \pm 0.2\text{V}$ ,  $V_{ddIN} = 1.5\text{V} \pm 0.1\text{V}$ ,  $V_{SS} = 0\text{V}$ )

PARAMETER	SYM	CONDITION	MIN.	MAX.	UNIT
PLL stable time	$t_{MCP\_PLL}$		10		ms
CGRESET* width time	$t_{MCK\_PLL}$		1		ms
RESET* width time	$t_{MCH\_PLL}$		1	-	ms

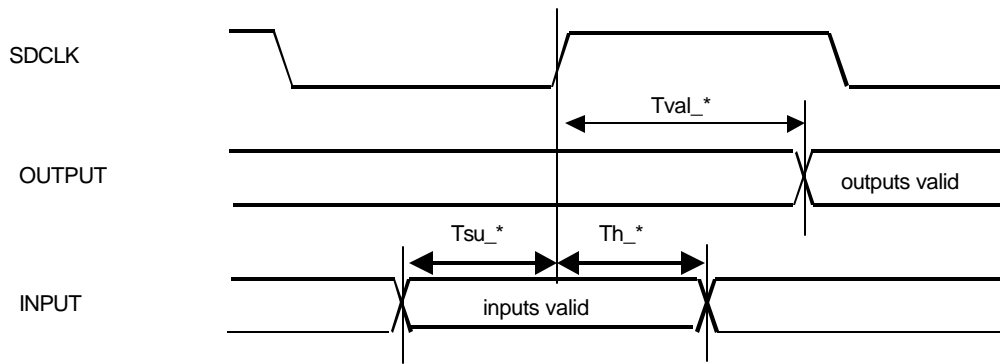


**SDRAM Interface AC Characteristics**

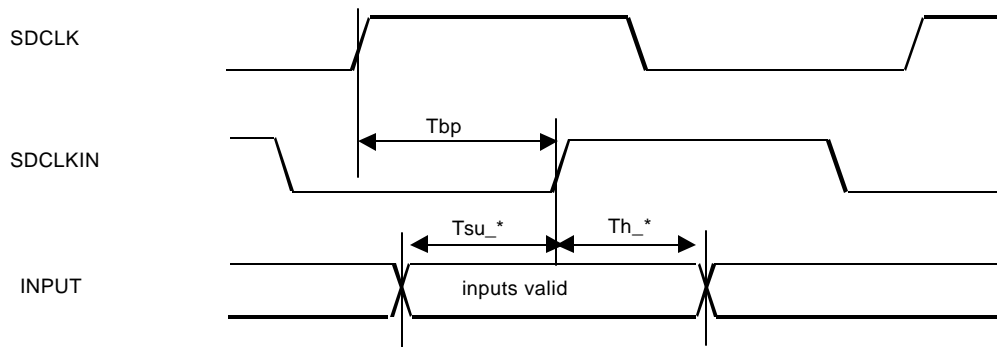
(T<sub>c</sub> = 0 ~ 70°C, V<sub>ddIO</sub> = 3.3V ± 0.2V, V<sub>ddIN</sub> = 1.5V ± 0.1V, V<sub>SS</sub> = 0V)

Signal Name	I/O	Load (pF)	Buffer Type	SYM	Descriptions	MIN (ns)	MAX (ns)
SDCLK[3:0]	O	50	16mA	Tcyc_sdclk	Clock Cycle Time	10	-
				Thigh_sdclk	Clock High Time	3	-
				Tlow_sdclk	Clock Low Time	3	-
SDCLKIN	I	-	-	Tbp	Clock Input Timing ( Non bypass mode )	0	4.0
ADDR[19:5]	O	150	16mA	Tval_addr1	Address Output Delay (*1)	1.5	6.5
SDCS[3:0]*	O	100	16mA	Tval_sdc	Output Delay for Chip Select	1.5	6.5
RAS*	O	150	16mA	Tval_ras	Output Delay for RAS* (*1)	1.5	6.5
CAS*	O	150	16mA	Tval_cas	Output Delay for CAS* (2 Cycle Bus Operation)	1.5	6.5
WE*	O	150	16mA	Tval_we	Output Delay for Write Enable (2 Cycle Bus Operation)	1.5	6.5
CKE	O	150	16mA	Tval_cke	Output Delay for Clock Enable	1.5	6.5
DQM[7:0]	O	50	16mA	Tval_dqm	Output Delay for Data Mask (*1)	1.5	6.5
DATA[63:0]	I/O	50	16mA	Tval_data1	Output Delay for Data (High <->low) (*1)	1.5	6.5
				Tval_data1v	Output Delay for Data (Hi-Z -> valid)	1.5	6.5
				Tval_data1z	Output Delay for Data (valid->Hi-Z)	1.5	6.5
	-	-	-	Tsu_data1b	Data Setup Time (Bypass mode)	4.0	-
	-	-	-	Th_data1b	Data Hold Time (Bypass mode)	0.5	-
	-	-	-	Tsu_data1nb	Data Setup Time (Non bypass mode)	1.5	-
	-	-	-	Th_data1nb	Data Hold Time (Non bypass mode)	1.0	-

(\*1) An SDRAM bus transaction can complete in no more than two clock cycles through programming the SDRAMC and Configuration registers.



**Output Signals and when bypass mode input Signals (SDCLK basis)**



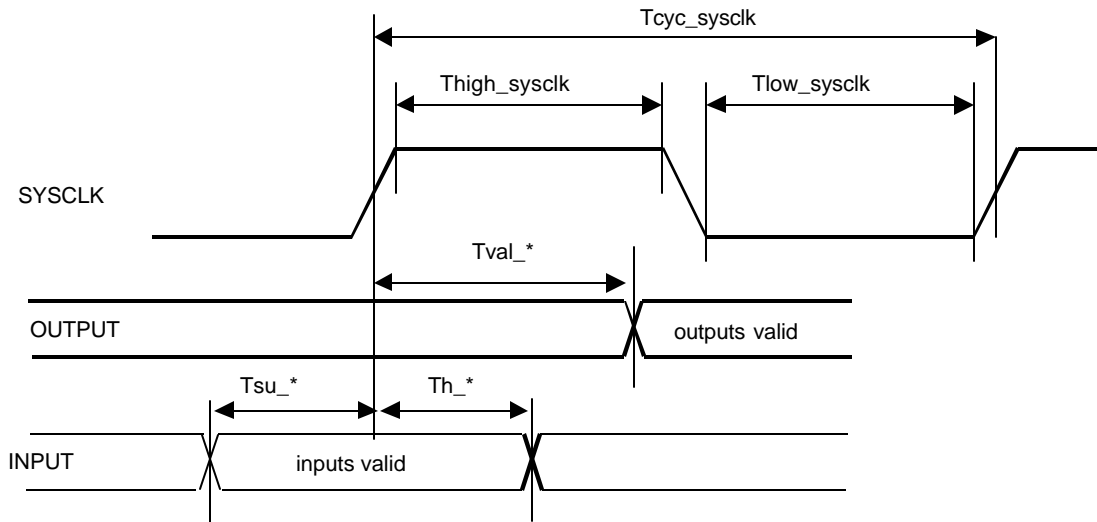
**When non bypass mode input signals (SDCLK basis)**



**External Bus Interface AC Characteristics**

(Tc = 0 ~ 70°C, VddIO = 3.3V ± 0.2V, VddIN = 1.5V ± 0.1V, VSS = 0V)

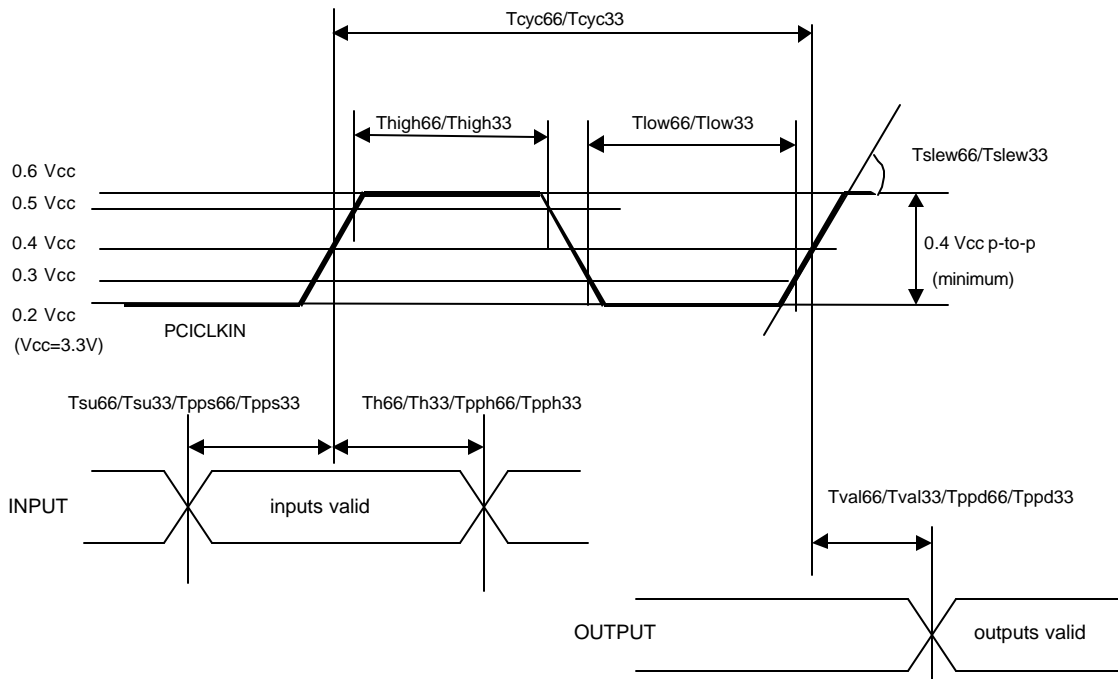
Signal Name	I/O	Load (pF)	Buffer Type	SYM	Descriptions	MIN (ns)	MAX (ns)
SYSCLK	O	50	8mA(fix)	Tcyc_sysclk	Clock Cycle Time	10	-
				Thigh_sysclk	Clock High Time	4	-
				Tlow_sysclk	Clock Low Time	4	-
ADDR[19:5]	O	150	16mA	Tval_addr2	Output Delay for Address	1.5	6.5
CE[7:0]*	O	50	8mA(fix)	Tval_ce	Output Delay for Chip Enable	1.5	8.5
OE*	O	50	8mA(fix)	Tval_oe	Output Delay for Output Enable	1.5	8.5
SWE*	O	50	8mA(fix)	Tval_swe	Output Delay for Write Enable	1.5	8.5
BWE*[3:0]	O	50	8mA(fix)	Tval_bwe	Output Delay for Byte Enable	1.5	8.5
ACE*	O	50	8mA(fix)	Tval_ace	Output Delay for Address Clock Enable	1.5	8.5
BUSSPRT*	O	50	8mA(fix)	Tval_bus	Output Delay for Bus Separate	1.5	8.5
DATA[31:0]	I/O	50	16mA	Tval_data2	Output Delay for Data (High <-> Low)	1.5	6.5
				Tval_data2v	Output Delay for Data (Hi-Z -> valid)	1.5	8.5
				Tval_data2z	Output Delay for Data (valid -> Hi-Z)	1.5	8.5
		-	-	Tsu_data2	Data Setup Time	6.0	-
		-	-	Th_data2	Data Hold Time	0.5	-
ACK*	I/O	50	8mA(fix)	Tval_ack	Output Delay for ACK* (High <-> Low)	1.5	8.5
				Tval_ackv	Output Delay for ACK* (Hi-Z -> valid)	1.5	6.5
				Tval_ackz	Output Delay for ACK* (valid -> Hi-Z)	1.5	8.5
		-	-	Tsu_ack	ACK* Setup Time	6.0	-
		-	-	Th_ack	ACK* Hold Time	0.5	-



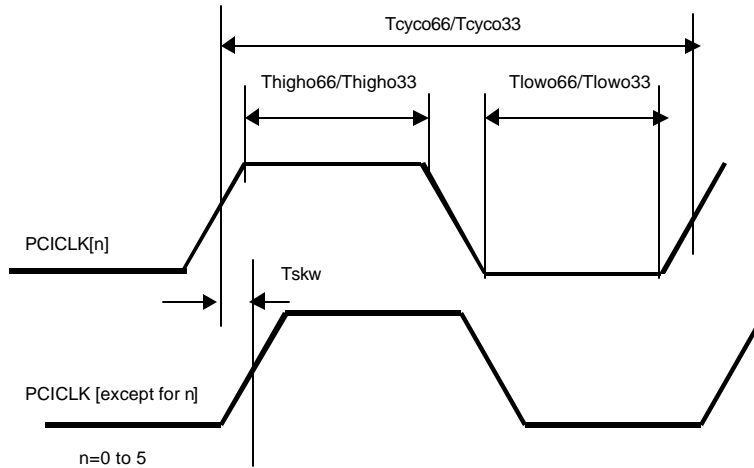
**External Bus Interface**

**PCI Interface AC Characteristics**

Signal Name	I/O	PCI-bus Spec.	Load (pF)	SYM	Descriptions	MIN (ns)	MAX (ns)		
PCICLKIN	I	66MHz	-	Tcyc66	Input Clock Cycle Time	15	30		
				Thigh66	Input Clock High Time	6	-		
				Tlow66	Input Clock Low Time	6	-		
				Tslew66	Input Clock Through rate [V/ns]	1.5	4		
		33MHz	-	Tcyc33	Input Clock Cycle Time	30	40		
				Thigh33	Input Clock High Time	11	-		
				Tlow33	Input Clock Low Time	11	-		
PCICLK[5:0]	O	66MHz	50	Tcyco66	Output Clock Cycle Time	15	30		
				Thigho66	Output Clock High Time	6	-		
				Tlowo66	Output Clock Low Time	6	-		
		33MHz	70	Tcyco33	Output Clock Cycle Time	30	40		
				Thigho33	Output Clock High Time	11	-		
				Tlowo33	Output Clock Low Time	11	-		
		-	50	Tskw	Output Clock Slew (point to point connection)	0	TBD		
PCIAD[31:0] C_BE[3:0] PAR FRAME* IRDY* TRDY* STOP* DEVSEL* PERR* SERR* LOCK* M66EN PME*	I/O I/O I/O I/O I/O I/O I/O I/O I/O I/O O3	66MHz	30	Tval66	Output Delay (bus connection)	2	8		
				Tsu66	Setup Time (bus connection)	3	-		
				Th66	Hold Time (bus connection)	0.5	-		
		33MHz	70	Tval33	Output Delay (bus connection)	2	8		
				Tsu33	Setup Time (bus connection)	5	-		
				Th33	Hold Time (bus connection)	0	-		
		ID_SEL REQ[3:0]* GNT[3:0]*	I I/O I/O	66MHz	30	Tppd66	Output Delay (point to point connection)	2	11
						Tpps66	Setup Time (point to point connection)	7	-
Tpph66	Hold Time (point to point connection)					0.5	-		
33MHz	70			Tppd33	Output Delay (point to point connection)	2	12		
				Tpps33	Setup Time (point to point connection)	10	-		
				Tpph33	Hold Time (point to point connection)	0	-		

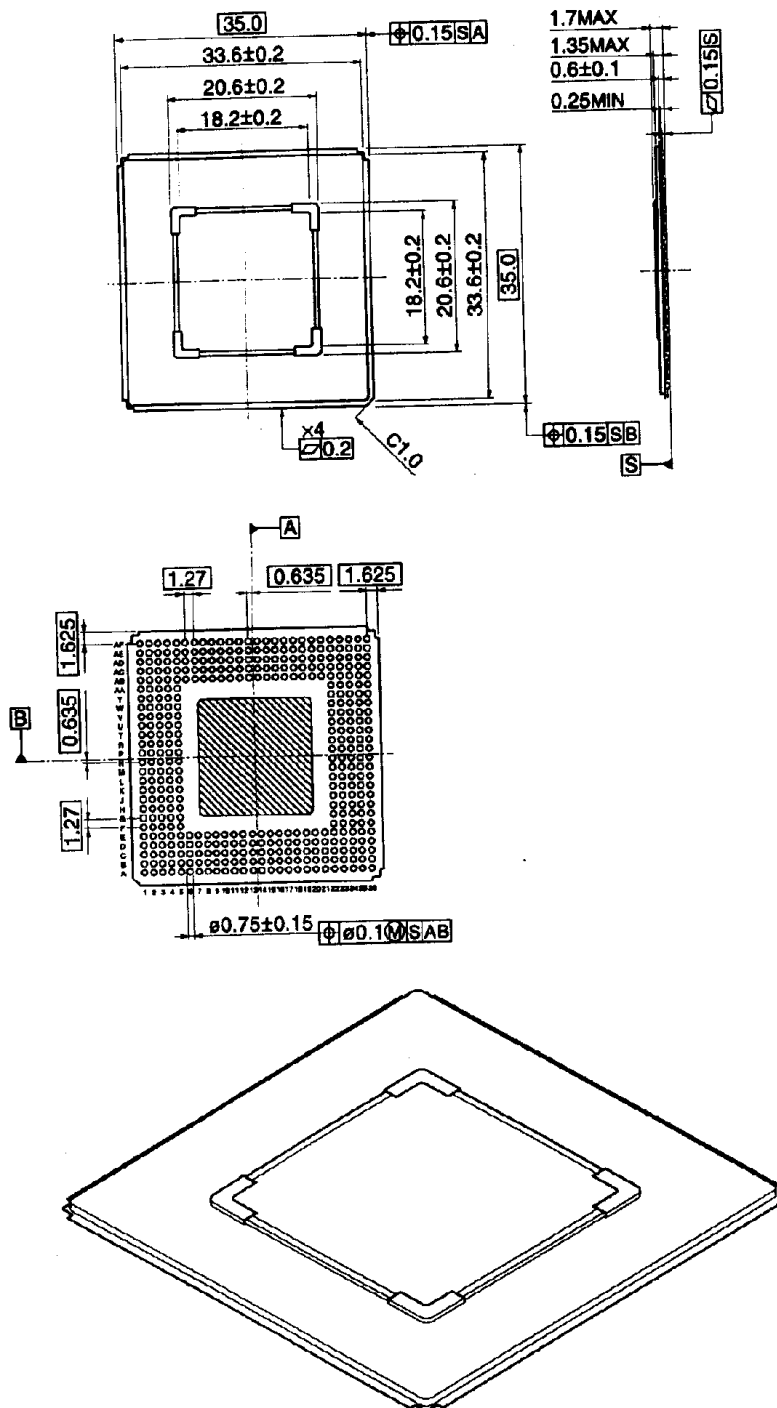


**PCI Interface (3.3V)**



**PCI Clock Skew**

**6. Package**



## 7. HISTORY

28/Aug/00 Modify the description for SDRAM Controller  
Modify Pin layout  
Modify from DFS signal to TEST2 signal  
13/Jan/01 Added the Package Diagram  
22/Jan/01 DC/AC Timing  
26/Jan/01 Modify the description  
6/Feb/01 Modify the description  
20/Aug/01 Modify the Signal description and AC Characteristics  
17/Jan/02 Modify the product name  
TMPR4927TB -> TMPR4927ATB-200  
Modify the spec of AC and DC